









PCB Number: TIDM-TM4C129USBHS PCB  
 PCB Rev. A0  
 TEXAS INSTRUMENTS  
 LOGO  
 Texas Instruments  
 Pb-Free Symbol

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 Orderable: No  
 TID #: TIDM-TM4C129USBHS  
 Number: TIDM-TM4C129USBHS  
 Rev: Version control disabled  
 Assembly Variant: No Variations  
 Drawn By: Amlit Ashara  
 Engineer: Amlit Ashara  
 Designed for: Public Release  
 Project Title: USB High Speed for TM4C129x  
 Sheet Title: Assembly Variant (No Variations)  
 File: TIDM-TM4C129USBHS\_USB\_SchDoc  
 Contact: <http://www.ti.com/support>  
 Mod. Date: 3/3/2016  
 Sheet 4 of 4  
 Size: B  
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